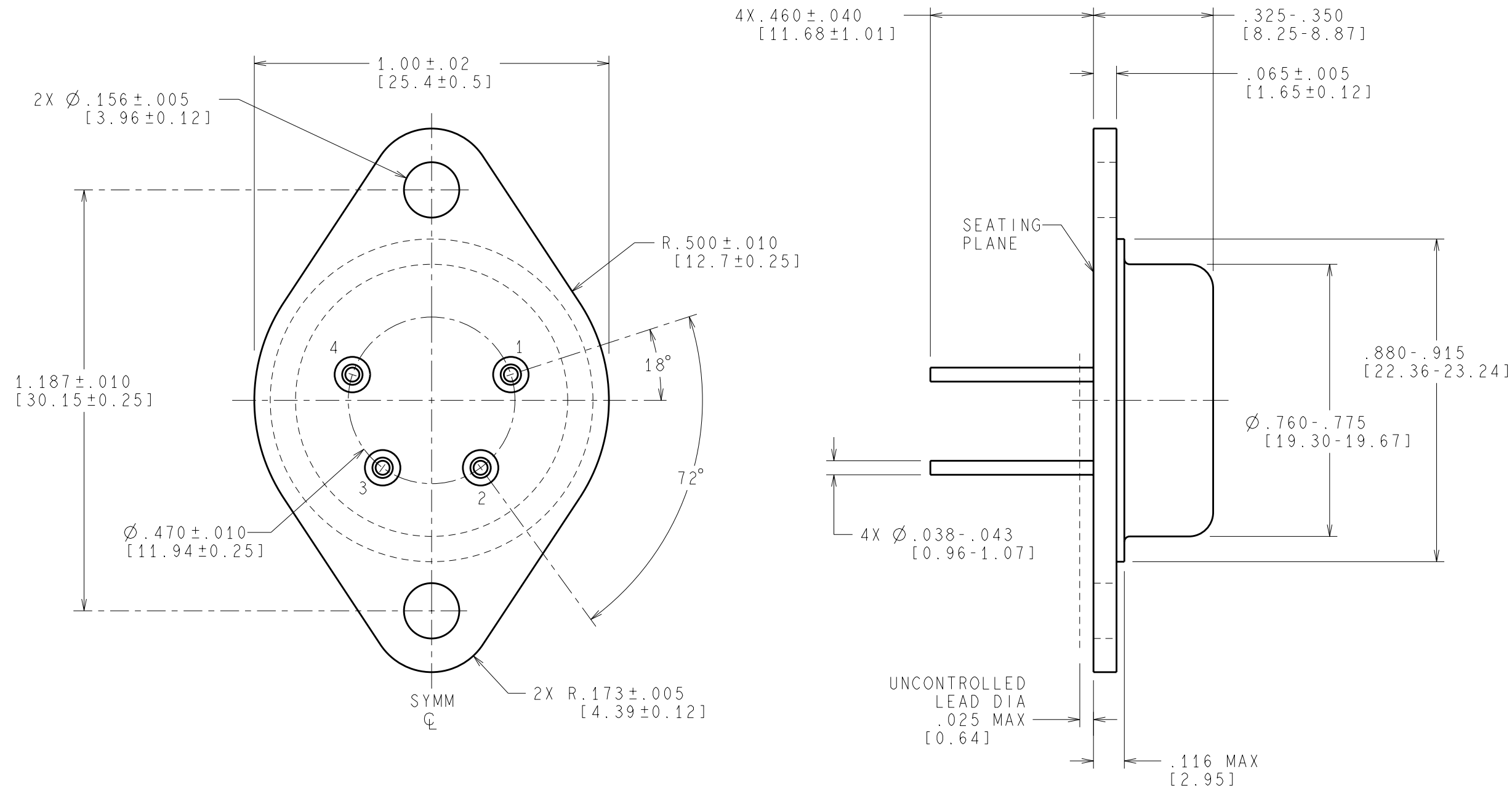


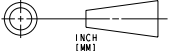
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
F	REVISE & REDRAW; .420-.500 WAS .420-.480; .ADD NOTE 3	08825	10/28/1991	TL/FL
G	REVISE & REDRAW PER CURRENT STD; CHANGE DWG FORMAT TO B SIZE	740	07/08/2002	TL/CD



NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD HEADER TYPE SOLID BASE.
- STANDARD LEAD FINISH:
Sn/Pb SOLDER OVER 100 MICROINCHES [2.54 MICROMETERS]
MINIMUM NICKEL PLATED ON ALLOY 52.
- LEAD TIPS LOCATED WITHIN $\pm .080$ [2.03] OF LEAD POSITION
AT BASE.
- REFERENCE JEDEC STANDARD, PUBLICATION 95, TO-3.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	T. LEQUANG	07/08/2002		
DTG. CHK.	KURT SINCERBOX	07/08/2002		
ENGR. CHK.	CORNEL DEVERA	07/08/2002		
			METAL CAN (KA), TO-3, 4 LEAD	
PROJECTION		SCALE	SIZE	DRAWING NUMBER
		NTS	B	(SC)MKT-K04A
FORMERLY: N/A			SHEET 1 of 1	